

### **Features**

- Superior circuit protection
- Overcurrent and overvoltage protection
- Blocks surges up to rated limits
- High-speed performance
- Small SMT package
- Agency listing: ¶

### **Applications**

- Voice / VDSL cards
- Protection modules and dongles
- Process control equipment
- Test and measurement equipment
- General electronics

UL

## TBU-CA Series - TBU® High-Speed Protectors

### **General Information**

The TBU-CA Series of Bourns® TBU® products are low capacitance single bidirectional high-speed protection components, constructed using MOSFET semiconductor technology, and designed to protect against faults caused by short circuits. AC power cross, induction and light

Line In/
Line Out
Line In

TBU® Device

Agency Listing

Description

File Number: E315805

circuits, AC power cross, induction and lightning surges.

The TBLI® high-speed protector placed in the system circ

The TBU® high-speed protector placed in the system circuit will monitor the current with the MOSFET detection circuit triggering to provide an effective barrier behind which sensitive electronics will not be exposed to large voltages or currents during surge events. The TBU® device is provided in a surface mount DFN package and meets industry standard requirements such as RoHS and Pb Free solder reflow profiles.

### Absolute Maximum Ratings (@ T<sub>A</sub> = 25 °C Unless Otherwise Noted)

Symbol	Parameter	Part Number	Value	Unit
		TBU-CA025-xxx-WH	250	
		TBU-CA040-xxx-WH	400	
V <sub>imp</sub>	Peak impulse voltage withstand with duration less than 10 ms	TBU-CA050-xxx-WH	500	V
'		TBU-CA065-xxx-WH	650	
		TBU-CA085-xxx-WH	850	
		TBU-CA025-xxx-WH	100	
	Continuous A.C. RMS voltage	TBU-CA040-xxx-WH	200	
$V_{rms}$		TBU-CA050-xxx-WH	250	V
		TBU-CA065-xxx-WH	300	
		TBU-CA085-xxx-WH	425	
T <sub>op</sub>	Operating temperature range		-55 to +125	°C
T <sub>stg</sub>	Storage temperature range		-65 to +150	°C
T <sub>jmax</sub>	Maximum Junction Temperature	+125	°C	
ESD	HBM ESD protection per IEC 61000-4-2	±2	kV	

## **BOURNS**®

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www.bourns.com

<sup>\*</sup>RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011. Specifications are subject to change without notice.

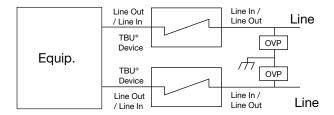
## Electrical Characteristics (@ $T_A$ = 25 °C Unless Otherwise Noted)

Symbol	Parameter	Min.	Тур.	Max.	Unit	
I <sub>trigger</sub>	Current required for the device to go from operation protected state	ng state to TBU-CAxxx-050-Wi TBU-CAxxx-100-Wi TBU-CAxxx-200-Wi TBU-CAxxx-300-Wi TBU-CAxxx-500-Wi	100 1 200 1 300	75 150 300 450 750	100 200 400 600 1000	mA
R <sub>device</sub>	Vimp = 250 V ltrigger (min Vimp = 400 V ltrigger (min Vimp = 500 V ltrigger (min Vimp = 650 V ltrigger (min Vimp = 850 V ltrigger	m.) = 100 mA m.) = 200 mA m.) = 300 mA m.) = 500 mA m.) = 300 mA m.) = 500 mA m.) =		13.3 7.1 4.2 3.2 2.6 14.3 8.1 5.2 4.3 3.6 15.7 9.5 6.6 5.0 17.7 11.5 8.6 7.6 7.0 21.4 15.2 12.3 11.3 10.7	15.3 8.2 4.8 3.8 3.0 16.5 9.4 6.0 5.0 4.2 18.0 10.9 7.5 6.5 5.7 20.3 13.2 9.8 8.8 8.0 24.5 17.4 14.0 13.0 12.2	Ω
t <sub>block</sub>	Time for the device to go from normal operating s			1	μs	
lQ	Current through the triggered TBU® device with 50	0.25	0.50	1.00	mA	
V <sub>reset</sub>	Voltage below which the triggered TBU® device w	te 12	16	20	V	
R <sub>th(j-l)</sub>	Junction to package pads - FR4 using recommen		98		°C/W	
R <sub>th(j-l)</sub>	Junction to package pads - FR4 using heat sink of		40		°C/W	

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### **Reference Application**

The TBU® devices are general use protectors used in a wide variety of applications. The maximum voltage rating of the TBU® device should never be exceeded. Where necessary, an OVP should be employed to limit the maximum voltage. A costeffective protection solution combines Bourns® TBU® protection devices with a pair of Bourns® MOVs. For bandwidth sensitive applications, a Bourns® GDT may be substituted for the MOV.



### **Basic TBU Operation**

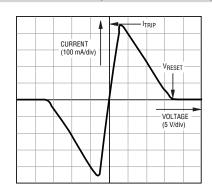
The TBU® device, constructed using MOSFET semiconductor technology, placed in the system circuit will monitor the current with the MOSFET detection circuit triggering to provide an effective barrier behind which sensitive electronics are not exposed to large voltages or currents during surge events. The TBU® device operates in approximately 1 µs - once line current exceeds the TBU® device's trigger current Itrigger. When operated, the TBU® device restricts line current to less than 1 mA typically. When operated, the TBU® device will block all voltages including the surge up to rated limits.

After the surge, the TBU® device resets when the voltage across the  $TBU^{\text{@}}$  device falls to the  $V_{reset}$  level. The  $TB\bar{U}^{\text{@}}$ device will automatically reset on lines which have no DC bias or have DC bias below V<sub>reset</sub> (such as unpowered signal lines).

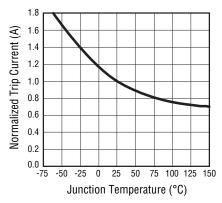
If the line has a normal DC bias above  $V_{reset}$ , the voltage across the TBU® device may not fall below V<sub>reset</sub> after the surge. In such cases, special care needs to be taken to ensure that the TBU® device will reset, with software monitoring as one method used to accomplish this. Bourns application engineers can provide further assistance.

### **Performance Graphs**

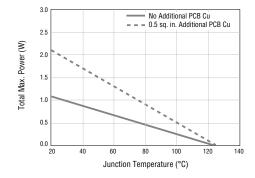
### Typical V-I Characteristics (TBU-CA050-300-WH)



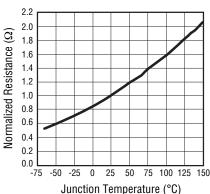
### Typical Trigger Current vs. Temperature



### **Power Derating Curve**



### Typical Resistance vs. Temperature

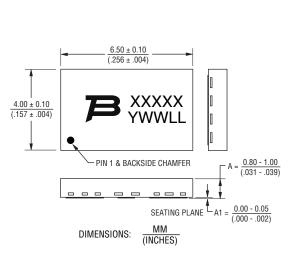


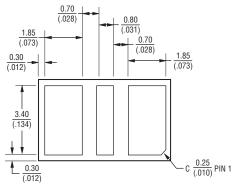
Specifications are subject to change without notice.

The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time. Users should verify actual device performance in their specific applications.

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### **Product Dimensions**



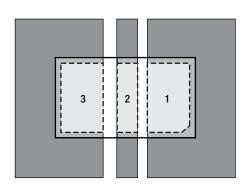


### **Pad Designation**

Pad #	Pin Out			
1	Line In/Out			
2	NU			
3	Line Out/In			

### **Recommended Pad Layout**

TBU® High-Speed Protectors have a 100 % matte-tin termination finish. For improved thermal dissipation, the recommended layout uses PCB copper areas which extend beyond the exposed solder pad. The exposed solder pads should be defined by a solder mask which matches the pad layout of the TBU® device in size and spacing. It is recommended that they should be the same dimension as the TBU® pads but if smaller solder pads are used, they should be centered on the TBU® package terminal pads and not more than 0.10-0.12 mm (0.004-0.005 in.) smaller in overall width or length. Solder pad areas should not be larger than the TBU® pad sizes to ensure adequate clearance is maintained. The recommended stencil thickness is 0.10-0.12 mm (0.004-0.005 in.) with a stencil opening size 0.025 mm (0.0010 in.) less than the solder pad size. Extended copper areas beyond the solder pad significantly improve the junction to ambient thermal resistance, resulting in operation at lower junction temperatures with a corresponding benefit of reliability. All pads should soldered to the PCB, including pads marked as NC or NU but no electrical connection should be made to these pads. For minimum parasitic capacitance, it is recommended that signal, ground or power signals are not routed beneath any pad.

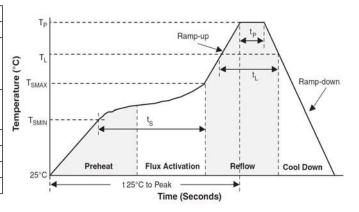


Dark grey areas show added PCB copper area for better thermal resistance.

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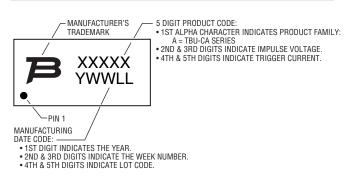
### **Reflow Profile**

Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate (Tsmax to Tp)	3 °C/sec. max.
Preheat - Temperature Min. (Tsmin) - Temperature Max. (Tsmax) - Time (tsmin to tsmax)	150 °C 200 °C 60-180 sec.
Time maintained above: - Temperature (TL) - Time (tL)	217 °C 60-150 sec.
Peak/Classification Temperature (Tp)	260 °C
Time within 5 °C of Actual Peak Temp. (tp)	20-40 sec.
Ramp-Down Rate	6 °C/sec. max.
Time 25 °C to Peak Temperature	8 min. max.

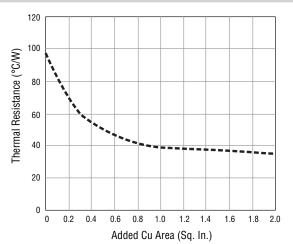


### **How to Order** TBU - CA 085 - 500 - WH TBU® Product Series CA = Bi-Series Impulse Voltage Rating 025 = 250 V 040 = 400 V050 = 500 V 065 = 650 V 085 = 850 V Trigger Current — 050 = 50 mA 100 = 100 mA200 = 200 mA 300 = 300 mA500 = 500 mAHold to Trip Ratio Suffix W = Hold to Trip Ratio Package Suffix H = DFN Package

### **Typical Part Marking**



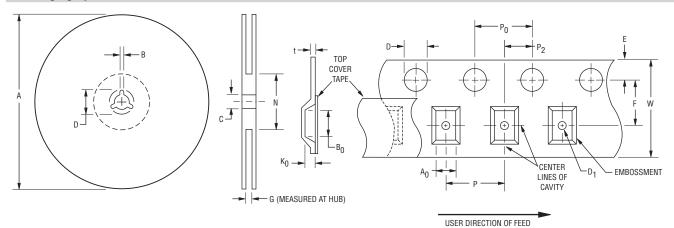
### Thermal Resistance vs Additional PCB Cu Area



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### **Packaging Specifications**



QUANTITY: 3000 PIECES PER REEL

Α		В		С		D		G	N
Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Ref.	Ref.
326	330	1.5	2.5	12.8	13.5	20.2		16.5	102
(12.835)	(13.002)	(.059)	(.098)	(.504)	(.531)	(.795)	_	(.650)	(4.016)

A <sub>0</sub>		B <sub>0</sub>		D		D <sub>1</sub>		E		F	
Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	max.
4.3 (.169)	4.5 (.177)	6.7 (.264)	6.9 (.272)	1.5 (.059)	1.6 (.063)	1.5 (.059)	-	1.65 (.065)	1.85 (.073)	7.4 (.291)	$\frac{7.6}{(.299)}$
K <sub>0</sub>		P		P <sub>0</sub>		P	2	, ,	t	\ \ \	V
Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
1.0	1.2	7.9	8.1	3.9	4.1	1.9	2.1	0.25	0.35	15.7	16.3
(.039)	$\overline{(.047)}$	(.311)	(.319)	(.159)	(.161)	(.075)	(.083)	(.010)	(.014)	(.618)	(.642)

DIMENSIONS:

(INCHES)

# **Mouser Electronics**

**Authorized Distributor** 

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

### Bourns:

TBU-CA025-050-WH TBU-CA025-100-WH TBU-CA025-200-WH TBU-CA025-300-WH TBU-CA025-500-WH TBU-CA025-500-WH TBU-CA040-050-WH TBU-CA040-100-WH TBU-CA040-200-WH TBU-CA040-300-WH TBU-CA040-500-WH TBU-CA050-050-WH TBU-CA050-100-WH TBU-CA050-200-WH TBU-CA050-300-WH TBU-CA050-500-WH TBU-CA065-050-WH TBU-CA065-050-WH TBU-CA065-050-WH TBU-CA065-050-WH TBU-CA085-050-WH TBU-CA